**MATERIAL DECLARATION DATA SHEET**

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<th>Device Name</th>
<th>Package Type</th>
<th>Pkg Wt (g)</th>
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<th>CAS No.</th>
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<th>Substance Mass (%)</th>
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# MATERIAL DECLARATION DATA SHEET

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<th>Material Breakdown of Component</th>
<th>Material Breakdown (%)</th>
<th>Substance Name</th>
<th>CAS No.</th>
<th>Weight (g)</th>
<th>Substance Mass (%)</th>
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### MATERIAL DECLARATION DATA SHEET

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#### Material Breakdown of Component

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<tr>
<th>Material Breakdown of Component</th>
<th>Material Breakdown (%)</th>
<th>Substance Name</th>
<th>CAS No.</th>
<th>Weight (g)</th>
<th>Substance Mass (%)</th>
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## MATERIAL DECLARATION DATA SHEET

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### Material Breakdown of Component

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<th>Substance Name</th>
<th>CAS No.</th>
<th>Weight (g)</th>
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